



GUJARAT TECHNOLOGICAL UNIVERSITY

Program Name: Master of Engineering

Level: PG

Branch: Electronics And Communication (VLSI Design)

Subject Code: ME02096031

Subject Name: Semiconductor Memory Circuits Design

| | |
|------------------------|---------|
| WEF Academic Year | 2025-26 |
| Semester | 02 |
| Category of the Course | PEC-03 |

| | |
|----------------------|--|
| Prerequisite: | Basic analog and digital CMOS circuits |
| Rationale: | Currently, there are requirement of high speed, excellent performance and huge capacity of memory chips due to advances in computing technologies and AI/ML based systems. The student in the course learns contemporary concepts of various design methodologies of emerging volatile/nonvolatile memories, various fault models and testing procedures for semiconductor memories, and advanced memory technologies for future requirements. |

Course Outcome:

After Completion of the Course, Student will be able to:

| No | Course Outcomes | RBT Level* |
|----|---|------------|
| 01 | Analyze operation of different SRAM and DRAM. | AN |
| 02 | Analyze operation of different non-volatile semiconductor memories. | AN |
| 03 | Model different memory faults. | AP |
| 04 | Analyze memory testing techniques. | AN |
| 05 | Evaluate advanced memory technologies. | EL |

*RM: Remember, UN: Understand, AP: Apply, AN: Analyze, EL: Evaluate, CR: Create

Course Scheme:

| Teaching Scheme | | | Total Credits | Assessment Pattern and Marks | | | | Total Marks |
|-----------------|----|----|---------------|------------------------------|-------|-----------|--------|-------------|
| L | T | PR | C | Theory | | Practical | | |
| | | | | ESE (E) | PA(M) | ESE (V) | PA (I) | |
| 03 | 00 | 02 | 00 | 70 | 30 | 30 | 20 | 150 |



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Course Content:

| U. No | Course Content | No of Hours | % weightage |
|-------|---|-------------|-------------|
| 1 | Random Access Memory Techniques: Introduction, static random-access memories (SRAMs): SRAM (NMOS and CMOS cell structures, MOS SRAM architectures, MOS SRAM cell and peripheral circuit operation, bipolar SRAM technologies, Silicon-on-Insulator (SOI) technology, advanced SRAM architectures and technologies, application-specific SRAMs. Dynamic Random-Access Memories (DRAMs), DRAM technology development, CMOS DRAMs, DRAM cell theory and advanced cell structures, BiCMOS DRAMs, soft-error failures in DRAMs, advanced DRAM designs and architectures, a 16-Mb DRAM, ULSI DRAM developments. Application-Specific DRAMs: Pseudo static DRAMs, silicon file, video DRAMs, high-speed DRAMs, application-specific RAM glossary and summary. | 10 | 25 |
| 2 | Nonvolatile Memories: Introduction, Masked Read-Only memories (ROMs): technology development and cell programming, ROM cell structures, high-density ROMs. Programmable Read-Only memories (PROMs): bipolar PROMs, CMOS PROMs. Erasable -Programmable Read-Only Memories (EPROMs): floating-gate EPROM cell, EPROM technology developments, advanced EPROM architectures, OTP EPROMs. Electrical Erasable PROMs (EEPROMs): EEPROM technologies, EEPROM architectures, nonvolatile SRAM. Flash memories (EPROMs/EEPROMs): flash memory cells and technology developments, advanced flash memory architectures. | 8 | 20 |
| 3 | Memory Fault Modeling and Testing: Introduction, RAM fault modeling: stuck-at faulty model, bridging faults, coupling faults, pattern-sensitive faults, miscellaneous faults, GaAs SRAM fault modeling and testing, embedded DRAM faulty modeling and testing. RAM Electrical Testing: DC and AC parametric testing, functional testing and some commonly used algorithms, functional test pattern selection. RAM pseudorandom testing, megabit DRAM testing, nonvolatile memory modeling and testing: DC electrical measurements, AC and functional measurements. IDDQ fault modeling and testing, application specific memory testing. | 8 | 20 |
| 4 | Memory Design for Testability and Faulty Tolerance: general design for testability techniques: Ad Hoc design techniques, structured design techniques. RAM Built-In Self-Test (BIST): BIST using algorithmic test sequence, BIST using 13N March algorithm, BIST for pattern-sensitive faults, BIST using BILBO. Embedded memory DFT and BIST techniques, Advanced BIST and Built-In Self-Repair architectures, DFT and BIST for ROMs, memory error detection and correction techniques, memory fault-tolerance designs | 10 | 25 |



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|---|---|----|-----|
| 5 | Advanced Memory Technologies: Introduction, Ferroelectric RAMs (FRAMS): basic theory, FRAM cell and memory operation, FRAM technology developments, FRAM reliability issues, FRAM radiation effects, FRAMS Vs EEPROMs. GaAs FRAMS, analog memories, magnetoresistive RAMs (MRAMs), experimental memory devices: quantum-mechanical switch memories, a GaAs n-p-n-p Thyristor/JFET memory cell, single electron memory, neuron-MOS multiple-valued memory technology. | 6 | 10 |
| | | 42 | 100 |

Reference Book:

- Ashok K. Sharma, Advanced Semiconductor Memories: Architectures, Designs, and Applications, Wiley Interscience, 1997.
- Luecke Mize Care, “Semiconductor Memory design & application”, Mc-Graw Hill.

Suggested Course Practical List:

- The practical work will be carried out based on the content covered during the academic session.

List of Laboratory/Learning Resources Required:

- List of Hardware: FPGA/CPLD programming tool, Multimeter, Power supply, function generator, oscilloscope
- List of Software: EDA Tools – Cadence, Synopsis, Siemens
- List of Useful websites MOOCs:---
 - Course-related online MOOCs on NPTEL/SWAYAM platform
 - Recent publications in reputed journal/conferences
